

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Count
1	BRS	48 77	laser with interconnect\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:52		0
2	BRS	39 5	second with laser with interconnect\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/01 19:40		0
3	BRS	1	second with laser with interconnect\$6 and control\$6 near collaps\$6 near chip near connect\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 14:30		0
4	BRS	3	second with laser with interconnect\$6 and (control\$6 near collaps\$6 near chip near connect\$6 or c4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/01 19:39		0
5	BRS	15	second with laser with interconnect\$6 and solder adj ball	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/01 19:41		0
6	BRS	18	second with laser with interconnect\$6 and solder adj (ball or paste)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/01 19:49		0
7	BRS	2	second near laser with interconnect\$6 and solder adj (ball or paste)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/01 19:50		0
8	BRS	19	second with energ\$6 with laser with interconnect\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/01 19:52		0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Info
9	BRS	176	laser with interconnect\$6 with weld\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:13		0
10	BRS	108	laser with interconnect\$6 and (control\$6 near collaps\$6 near chip near connect\$6 or c4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 14:31		0
11	BRS	14	laser with interconnect\$6 and (control\$6 near collaps\$6 near chip near connect\$6 or c4) and weld\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 14:53		0
12	BRS	139	laser with weld\$6 and (control\$6 near collaps\$6 near chip near connect\$6 or c4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 15:00		0
13	BRS	97	laser near weld\$6 and (control\$6 near collaps\$6 near chip near connect\$6 or c4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 14:54		0
14	BRS	6	laser near weld\$6 and (control\$6 near collaps\$6 near chip near connect\$6 or c4) and solder adj ball and solder adj paste	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 14:55		0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error
15	BRS	13	laser with weld\$6 and (control\$6 near collaps\$6 near chip near connect\$6 or c4) and solder adj ball and solder adj paste	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 15:23		0
16	BRS	33	4535219.URPN.	USPAT	2004/08/03 15:06		0
17	BRS	17	laser with (weld\$6 or bond\$6) and (control\$6 near collaps\$6 near chip near connect\$6 or c4) and solder adj ball and solder adj paste	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 15:25		0
18	BRS	20 7	laser with (bond\$6 or weld\$6) and	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:14		0
19	BRS	54	laser with (bond\$6 or weld\$6) and mcm and solder near ball	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:14		0
20	BRS	20	laser with (bond\$6 or weld\$6) and mcm and solder near ball and solder near paste	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:29		0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error	Errors
21	BRS	6	laser with (bond\$6 or weld\$6) and mcm and solder near ball and solder near paste and (c4 or control\$6 near collaps\$6 near chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:30			0
22	BRS	17	laser with (bond\$6 or weld\$6) and solder near ball and solder near paste and (c4 or control\$6 near collaps\$6 near chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:32			0
23	BRS	74	laser with (bond\$6 or weld\$6) and solder near ball and (c4 or control\$6 near collaps\$6 near chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:32			0
24	BRS	12	laser with (bond\$6 or weld\$6) and mcm and solder near ball and (c4 or control\$6 near collaps\$6 near chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:41			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Info
25	BRS	12	laser with (reflow\$6 or bond\$6 or weld\$6) and mcm and solder near ball and (c4 or control\$6 near collaps\$6 near chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:42		0
26	BRS	78	laser with (reflow\$6 or bond\$6 or weld\$6) and solder near ball and (c4 or control\$6 near collaps\$6 near chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:42		0
27	BRS	22	laser with (reflow\$6 or bond\$6 or weld\$6) and solder near ball and (c4 or control\$6 near collaps\$6 near chip) and paste	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:42		0
28	BRS	20	laser with (reflow\$6 or bond\$6 or weld\$6) and solder near ball and (c4 or control\$6 near collaps\$6 near chip) and solder with paste	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:43		0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Errors
29	BRS	20	laser with (reflow\$6 or bond\$6 or weld\$6) and solder with ball and (c4 or control\$6 near collaps\$6 near chip) and solder with paste	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:43		0
30	BRS	126	second with chip with bond\$6 with laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 14:11		0
31	BRS	11	stack\$6 near chip with bond\$6 with laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 14:45		0
32	IS&R	2	("6133626").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 15:24		0
33	IS&R	2	("20040012938").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 16:08		0
34	IS&R	2	("6451626").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 16:54		0
35	BRS	147	bond\$6 with (chip or die) with package with laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 16:55		0
36	BRS	20	bond\$6 with (chip or die) with package with laser and solder adj	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 18:07		0
37	BRS	3688	ball\$6 with (chip or die) with package and solder adj ball	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:52		0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Ratio
38	BRS	0	bond\$6 with (chip or die) with intreposer with package and solder adj	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 18:07		0
39	BRS	12 6	bond\$6 with (chip or die) with interposer with package and solder adj	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 18:08		0
40	BRS	3	bond\$6 with (chip or die) with interposer with package and solder adj ball and laser with (heat\$6 or reflow\$6 or melt\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 18:09		0
41	BRS	58	bond\$6 with (chip or die) with interposer with package and solder adj	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 19:12		0
42	BRS	1	bond\$6 with die with package with solder adj	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 19:14		0
43	BRS	1	bond\$6 with die with package with solder adj	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 19:14		0
44	BRS	80	bond\$6 with die with package with solder adj ball and laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 19:15		0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Count	Error Info
45	BRS	22	bond\$6 with die with package with solder adj ball and laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 19:15		0	
46	BRS	0	bond\$6 with (chip or die) with package and solder adj ball and "double data rate memory"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:53		0	
47	BRS	14 0	"double data rate memory"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:53		0	
48	BRS	33	"double data rate memory" and interconnect\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:54		0	
49	BRS	3	"double data rate memory" and interconnect\$6 and bond\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 21:37		0	
50	BRS	2	"double data rate memory" and interconnect\$6 and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 21:38		0	